

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 73 and 91, and amend claims 70, 74, 77-84, 90, and 92-97 as follows:

Listing of Claims:

1-69. (Canceled)

70. (Currently Amended) A planarizing apparatus for planarization of microelectronic-device substrate assemblies, comprising:

a table for carrying a polishing pad;

a carrier assembly having a carrier head configured to hold a substrate assembly, the carrier head being movable to press the substrate assembly against the polishing pad, and at least one of the carrier head and the table being translatable with respect to the other to translate the substrate assembly across the polishing pad;

a slurry manufacturing assembly including:

a first supply of a first solution that has not been used to planarize a microelectronic substrate, the first solution having a plurality of first abrasive particles;

a first feed line in fluid communication with the first supply for containing a flow of the first solution;

a second supply of a second solution that has not been used to planarize a microelectronic substrate, the second solution having a plurality of second abrasive particles, the second solution being separate from the first solution;

a second feed line in fluid communication with the second supply for containing a separate flow of a second solution having a plurality of second abrasive particles;

a first removal unit coupled to the first feed line, the first removal unit configured to selectively remove a first type of selected abrasive particles from the first abrasive particles; and

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